

## Features

- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Solder dip 260 °C, 10 s
- Low profile, typical thickness 1.0mm



RoHS  
COMPLIANT

Package: eSGB(SMAF)

## Applications

For use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

## Maximum Ratings (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Symbol	LS32	LS33	LS34	LS35	LS36	LS37	LS38	LS39	LS3B	Unit
Maximum Repetitive Peak Reverse	V <sub>RRM</sub>	20	30	40	50	60	70	80	90	100	V
Maximum RMS Voltage	V <sub>RMS</sub>	14	21	28	35	42	49	56	63	70	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	20	30	40	50	60	70	80	90	100	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3.0									A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I <sub>FSM</sub>	100									A
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to + 150									°C

## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	LS32	LS33	LS34	LS35	LS36	LS37	LS38	LS39	LS3B	Unit
Maximum Instantaneous Forward Voltage	I <sub>F</sub> =3A	V <sub>F</sub>	0.55			0.70		0.85			V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	T <sub>A</sub> =25°C	I <sub>R</sub>	0.5									mA
	T <sub>A</sub> =125°C		20									
Typical Junction Capacitance	4.0 V, 1 MHz	C <sub>J</sub>	290			200		120			pF	
Typical Thermal Resistance	Junction to Lead	R <sub>θJL</sub> <sup>1)</sup>	25									°C/W

Note1: Thermal resistance from junction to lead, mounted on PCB with 0.315×0.315 inch (8.0×8.0mm) copper pads.

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

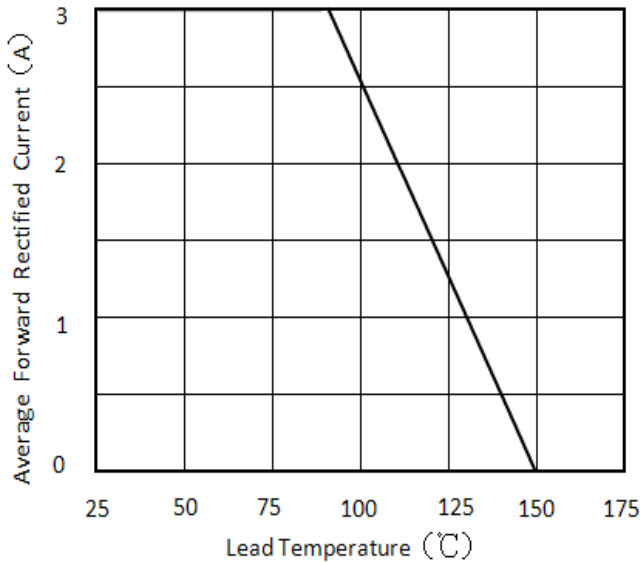


Figure 1. Forward Current Derating Curve

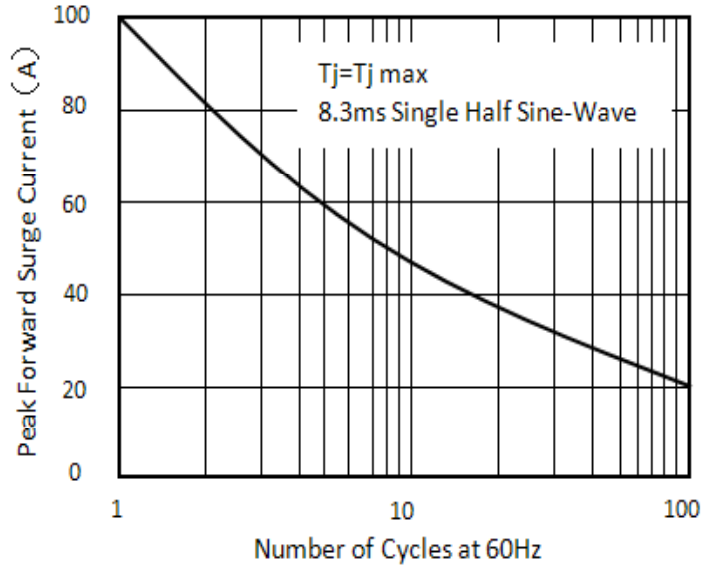


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

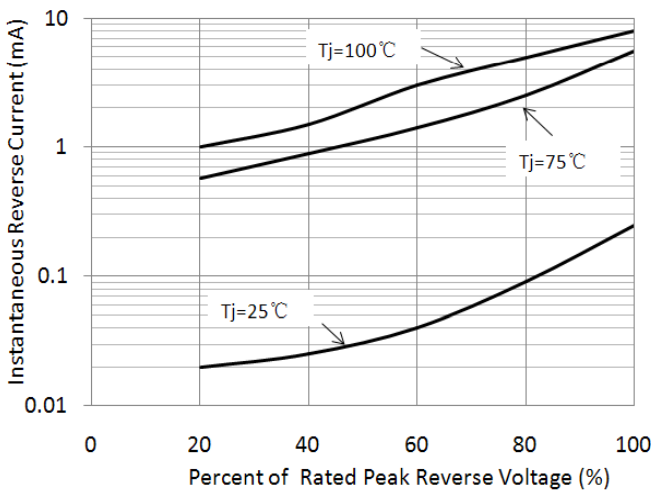


Figure 3. Typical Reverse Characteristics

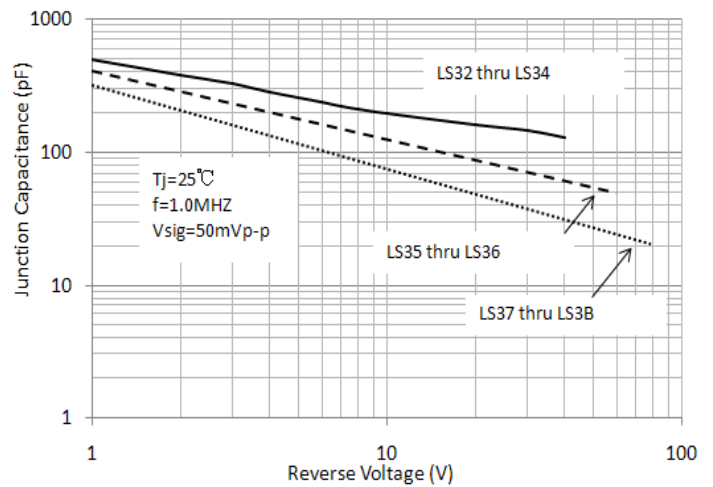


Figure 4. Typical Junction Capacitance

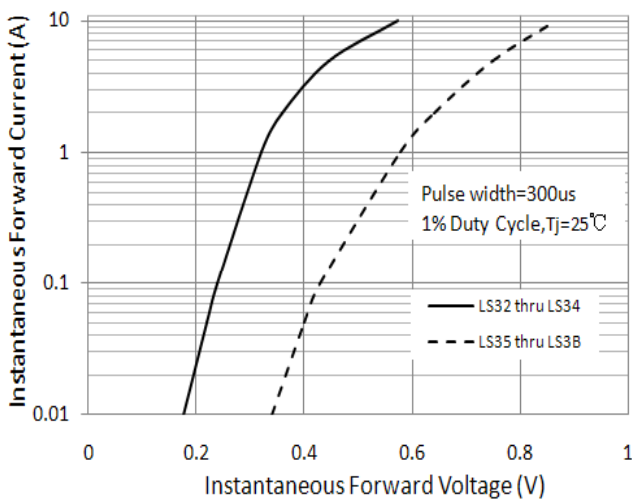
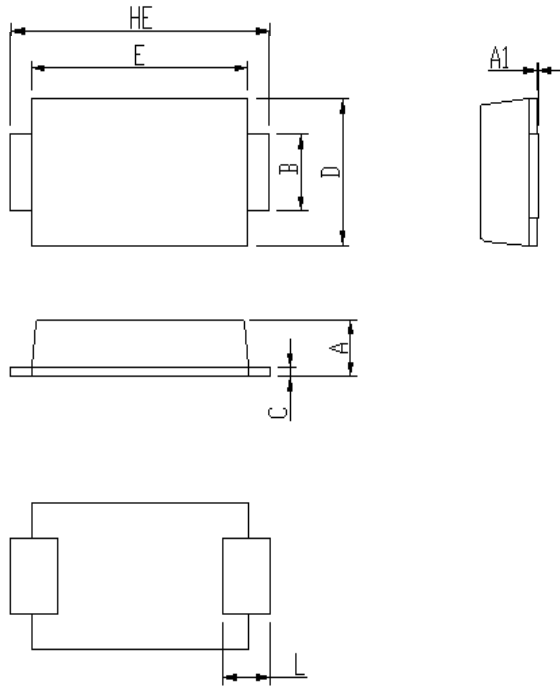


Figure 5. Typical Instantaneous Forward Characteristics

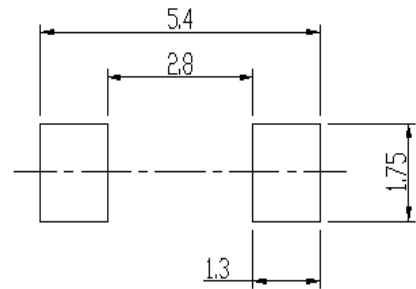
## Package Outline Dimensions

eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



## Packing Information

### Packing quantities

3,000 pcs/Reel , 12mm Tape, 13" Reel

### Tape & Reel Specification

